

## Conference Committees

### Conference Chair

Lu Li, National University of Singapore, Singapore

### Conference Co-Chair

Lihui Lang, Beihang University, China

### Program Chairs

Narayan C. Kar, University of Windsor, Canada

Jiangfeng Ni, Soochow University, China

### Program Co-Chair

Xuelin Lei, East China University of Science and  
Technology, China

### Steering Chairs

Takashige Omatsu, Chiba University, Japan

Han-Yong Jeon, Inha University, South Korea

### Publicity Chairs

Aidy Ali, National Defence University of Malaysia, Malaysia

Osman ADIGUZEL, Firat University, Turkey

Zhao Zexiang, Zhongyuan University of Technology, China

### Finance Chair

J.Wu, Hong Kong University, Hong Kong, China

### Publication Chair

Z.H. Gao, Dalian University, China

## Publication

The accepted papers with registration and presentation will be published into **Conference Proceedings**, which will be submitted to **Ei Compendex, Scopus**, etc.

## Publication History

### MIM 2019 | Inha University, South Korea

IOP Conference Series: Materials Science and  
Engineering (Volume 654)

Indexed by Scopus and Ei Compendex.

### MIM 2018 | Sapporo, Japan

MIM 2018: Materials Science Forum (Volume 962)-ISBN:  
978-3-0357-1416-6

Indexed by Scopus and Ei Compendex

### MIM 2017 | Singapore

IOP Conference Series: Materials Science and  
Engineering (Volume 244)

Indexed by Scopus and Ei Compendex

## Keynote Speakers



### Prof. Lu Li

National University of Singapore,  
Singapore



### Prof. Sung-Hoon Ahn

Seoul National University,  
South Korea



### Prof. Lihui Lang

Beihang University,  
China



### Prof. Jiangfeng Ni

Soochow University,  
China

## Conference Topics

### Materials Processing Technology and Materials Science

Materials Testing and Evaluation

Composite

Nanoscale Electronics

### Design and Manufacturing Systems

Virtual Manufacturing and Network Manufacturing

Advanced Manufacturing Technology

Recycling and Remanufacturing

More topics, please visit:

<http://www.icmim.org/cfp.html>

## Submission Info

**Submission Deadline: August 10, 2021**

### Electronic Submission System:

<http://confsys.iconf.org/submission/mim2021>

### Email Submission

icmim@cbees.net

